

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	14505	bare with (chip die ic (integrated adj circuit) semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/25 01:37
L2	14588	bare with (chip die ic (integrated adj circuit) semiconductor dice)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/25 01:37
L3	516	interpos\$4 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/25 01:38
L4	9324	2 same (carrier interpos\$4 substrate board pcb)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/25 01:39
L5	4397	(terminal contact electrode pad) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/25 01:42
L6	0	test@4 same 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/25 01:42
L7	731	test\$4 same 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/25 01:42

L8	1824	test\$4 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/25 01:43
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5/25/08 1:44:05 AM

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